

LOCTITE ABLESTIK 8008CSM

August 2013

PRODUCT DESCRIPTION

LOCTITE ABLESTIK 8008CSM provides the following product characteristics:

Technology	Proprietary Hybrid Chemistry Silver	
Appearance		
Cure	Heat cure	
Product Benefits	 Electrically conductive 	
	 Thermally conductive 	
	Low modulus	
	 Good substrate wetting 	
	 Controlled bondline thickness 	
Application	Die attach	
Filler Type	Silver	
Substrates	PPF, Copper and Silver-plated copper leadframes	

LOCTITE ABLESTIK 8008CSM adhesive is designed for medium die attach applications. This material can be applied to a wafer backside by stencil printing and then B-staged in an oven. The adhesive can then be cured after die attach in an in-line process.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	2.6		
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):			
Speed 5 rpm	67,500		
Work Life @ 25°C, hours	24		
Shelf Life @ -40°C, days	365		
Flash Point - See SDS			

TYPICAL PROCESS DATA

Recommended B-Stage Condition

10 minute ramp to 115°C + 60 minutes @ 115°C

TYPICAL CURING PERFORMANCE

Recommended Cure Schedule

30 minute ramp to 175°C + 60 minutes @ 175°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

	Thermal Conductivity, W/(m-K)	6
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Tensile Modulus, DMTA:		
@ -65 °C		7,702 (,119,550)
@ 25 °C	N/mm² 3	5,880 563,330)
@ 150 °C	N/mm² 1	,050 (52,430)
@ 200 °C	N/mm² 6	30 1,520)
@ 250 °C	N/mm² 4	40 3,820)
Extractable Ionic Content, @ 100°C ppm:	" / \	,
Chloride (CI-)		<10
Sodium (Na+)		<10
Potassium (K+)		<10
Weight Loss @ 250°C, %		0.2

Electrical Properties	
Volume Resistivity, ohms-cm	0.0005

TYPICAL PERFORMANCE OF CURED MATERIAL

Miscellaneous

Die Shear Strength:

3 x 3 mm Si die on Different Leadframes, kg-f	
Leadframe	@260°C
Ag/Cu Leadframe	2.7
Bare Cu Leadframe	2.5
Pd/Ni/Cu Leadframe	3

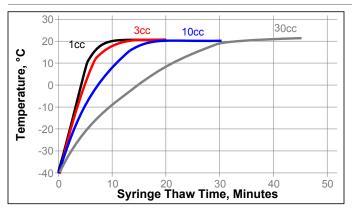
GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

- 1. Allow container to reach room temperature before use.
- After removing from the freezer, set the syringes to stand vertically while thawing.
- 3. Refer to the Syringe Thaw time chart for the thaw time recommendation.
- 4. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- 5. DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.





DIRECTIONS FOR USE

 Apply enough adhesive to the stencil to ensure complete filling of the stencil with a 20 to 50 mm diameter bead. Typically, this requires 20 to 50 cc of adhesive depending on the stencil size. For two-direction printing, double beading is recommended.

NOTE:

Please refer to the Wafer Backside Coating Applications and Data Package for this product to review process windows and recommendations for each step..

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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